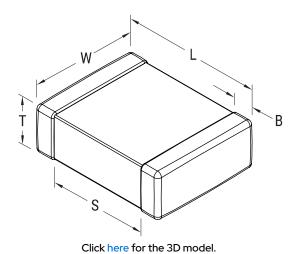


C2220X274G1TACTU

Aliases (C2220X274G1TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 0.27 uF, 2%, 100 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 2220, 3.5 mm



General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	190 mg
Shelf Life	78 Weeks
MSL	1

0.27 uF

3.7037 GOhms

Dimensions	
Chip Size	2220
L	5.9mm +/-0.75mm
W	5mm +/-0.4mm
Т	1.5mm +/-0.15mm
S	3.5mm MIN
В	0.7mm +/-0.35mm

5.9mm +/-0.75mm	Measurement Condition	1 kHz 1.0Vrms
5mm +/-0.4mm	Tolerance	2%
1.5mm +/-0.15mm	Voltage DC	100 VDC
3.5mm MIN	Dielectric Withstanding Voltage	250 VDC
0.7mm +/-0.35mm	Temperature Range	-55/+150°C
	Temp. Coefficient	X8G
	Capacitance Change with	30 ppm/C, 1kHz 1.0Vrms
T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
1000	Dissipation Factor	0.1% 1 kHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours

Insulation Resistance

Specifications

Capacitance

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Generated 05/03/2025 © 2006 - 2025 YAGEO